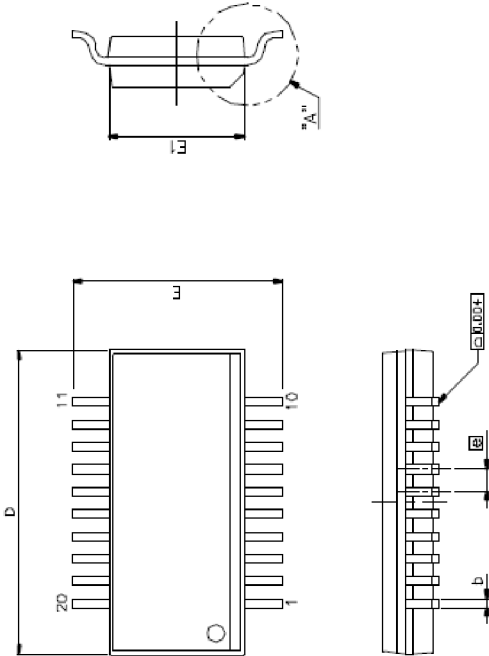


The F1231X is available in two different packages. The F1231XS is the SSOP-20 option and the F1231XQ is the QFN-20 package option. The solder reflow profile for both packages is described in Section 0.

9.1 SSOP-20 Package Mechanical Dimensions



SYMBOLS	MIN.	NOM.	MAX.
A	0.053	0.064	0.069
A1	0.004	0.006	0.010
A2	—	—	0.059
b	0.008	—	0.012
C	0.007	—	0.010
D	0.337	0.341	0.344
E	0.228	0.236	0.244
E1	0.150	0.154	0.157
E'	—	0.025 BASIC	—
L	0.016	0.025	0.050
L1	—	0.041 BASIC	—
Ø	0"	—	8"

UNIT : INCH

NOTES:

- 1.JEDEC OUTLINE : MO-137 AD
- 2.DIMENSION D DOES NOT INCLUDE MOLD PROTRUSIONS OR GATE BURRS. MOLD PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED 0.006" PER SIDE. DIMENSION E1 DOES NOT INCLUDE INTERLEAD MOLD PROTRUSIONS. INTERLEAD MOLD PROTRUSIONS SHALL NOT EXCEED 0.010" PER SIDE.